

50 mA, 100 mA, and 150 <u>mA CMOS LDOs</u> with Shutdown and Error Output

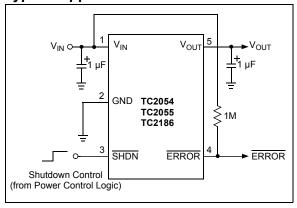
Features

- Low Supply Current (55 μA Typ.) for Longer Battery Life
- Low Dropout Voltage: 140 mV (Typ.) @ 150 mA
- High Output Voltage Accuracy: ±0.4% (Typ)
- · Standard or Custom Output Voltages
- · Power-Saving Shutdown Mode
- ERROR Output Can Be Used as a Low Battery Detector or Processor Reset Generator
- Fast Shutdown Reponse Time: 60 μsec (Typ)
- Overcurrent and Overtemperature Protection
- · Space-Saving 5-Pin SOT-23A Package
- · Pin Compatible Upgrades for Bipolar Regulators
- Standard Output Voltage Options:
 - 1.8V, 2.5V, 2.6V, 2.7V, 2.8V, 2.85V, 3.0V, 3.3V, 5.0V

Applications

- · Battery Operated Systems
- Portable Computers
- · Medical Instruments
- Instrumentation
- · Cellular / GSMS / PHS Phones
- Pagers

Typical Application



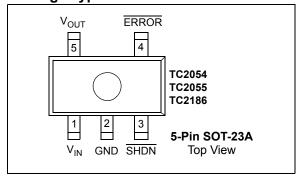
General Description

The TC2054, TC2055 and TC2186 are high accuracy (typically $\pm 0.4\%$) CMOS upgrades for older (bipolar) low dropout regulators. Designed specifically for battery-operated systems, the devices' total supply current is typically 55 μ A at full load (20 to 60 times lower than in bipolar regulators).

The devices' key features include low noise operation, low dropout voltage – typically 45 mV (TC2054); 90 mV (TC2055); and 140 mV (TC2186) at full load - and fast response to step changes in load. An error output (ERROR) is asserted when the devices are out-of-regulation (due to a low input voltage or excessive output current). Supply current is reduced to 0.5 μA (max) and both V_{OUT} and ERROR are disabled when the shutdown input is low. The devices also incorporate overcurrent and overtemperature protection.

The TC2054, TC2055 and TC2186 are stable with a low esr ceramic output capacitor of 1 μ F and have a maximum output current of 50 mA, 100 mA and 150 mA, respectively. This LDO Family also features a fast response time (60 μ s typically) when released from shutdown.

Package Type



1.0 **ELECTRICAL CHARACTERISTICS**

Absolute Maximum Ratings †

Input Voltage6.5V Output Voltage.....(-0.3) to (V_{IN} + 0.3) Operating Temperature-40°C < T_J< 125°C Storage Temperature.....-65°C to +150°C Maximum Voltage on Any PinV_{IN} +0.3V to -0.3V † Notice: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions above those indicated in the operation sections of the specifications is not implied. Exposure to Absolute Maximum Rating conditions for extended periods my affect device reliability.

ELECTRICAL SPECIFICATIONS

Electrical Specifications: Unless otherwise noted, $V_{IN} = V_R + 1V$, $I_L = 100 \mu A$, $C_L = 3.3 \mu F$, $\overline{SHDN} > V_{IH}$, $T_A = +25^{\circ}C$.

| BOLDFACE type specifications apply for junction temperature of -40°C to +125°C. | | | | | | | |
|--|---|-----------------------|----------------------|-----------------------|--------|---|--|
| Parameter | Sym | Min | Тур | Max | Units | Conditions | |
| Input Operating Voltage | V _{IN} | 2.7 | _ | 6.0 | V | Note 1 | |
| Maximum Output Current | IOUT _{MAX} | 50 100 150 | | _ _ _ | mA | TC2054 TC2055 TC2186 | |
| Output Voltage | V_{OUT} | V _R - 2.0% | $V_R \pm 0.4\%$ | V _R + 2.0% | V | Note 2 | |
| V _{OUT} Temperature Coefficient | TCV _{OUT} | 1 1 | 20 40 | | ppm/°C | Note 3 | |
| Line Regulation | ΔV _{OUT} / ΔV _{IN} | 1 | 0.05 | 0.5 | % | $(V_R + 1V) \le V_{IN} \le 6V$ | |
| Load Regulation | ΔV _{OUT} / V _{OUT} | -1.5 -2.5 | 0.5 0.5 | 0.5 0.5 | % | TC2054;TC2055 I_L = 0.1 mA to I_{MAX} TC2186 I_L = 0.1 mA to $I_{OUT_{MAX}}$ Note 4 | |
| Dropout Voltage, Note 5 | V _{IN} – V _{OUT} | 1111 | 2 45 90 140 | — 70 140 210 | mV | $\begin{array}{ccc} & I_L = 100 \; \mu\text{A} \\ & I_L = 50 \; \text{mA} \\ \text{TC2015; TC2185} & I_L = 100 \; \text{mA} \\ \text{TC2185} & I_L = 150 \; \text{mA} \\ \text{Note 5} \end{array}$ | |
| Supply Current | I _{IN} | _ | 55 | 80 | μA | SHDN = V _{IH} , I _L =0 | |
| Shutdown Supply Current | I _{INSD} | _ | 0.05 | 0.5 | μA | SHDN = 0V | |
| Power Supply Rejection Ratio | PSRR | | 50 | | dB | F _{RE} ≤ 100 kHz | |
| Output Short Circuit Current | I_{OUTSC} | 160 | 300 | _ | mA | V _{OUT} = 0V | |
| Thermal Regulation | $\Delta V_{OUT/}\Delta P_D$ | 1 | 0.04 | _ | V/W | Note 6 | |
| Thermal Shutdown Die Temperature | T _{SD} | _ | 160 | _ | °C | | |

- Note 1: The minimum V_{IN} has to meet two conditions: V_{IN} = 2.7V and V_{IN} = V_R + $V_{DROPOUT}$. 2: V_R is the regulator output voltage setting. For example: V_R = 1.8V, 2.7V, 2.8V, 2.85V, 3.0V, 3.3V.

3:
$$TCV_{OUT} = \frac{(V_{OUTMAX} - V_{OUTMIN}) \times 10^6}{V_{OUT} \times \Delta T}$$

- 4: Regulation is measured at a constant junction temperature using low duty cycle pulse testing. Load regulation is tested over a load range from 1.0mA to the maximum specified output current. Changes in output voltage due to heating effects are covered by the thermal regulation specification.
- 5: Dropout voltage is defined as the input to output differential at which the output voltage drops 2% below its nominal value at a 1V differential.
- 6: Thermal Regulation is defined as the change in output voltage at a time T after a change in power dissipation is applied, excluding load or line regulation effects. Specifications are for a current pulse equal to I_{MAX} at V_{IN} = 6V for T = 10 ms.
- 7: The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction-to-air (i.e. $T_A,\,T_J,\,\theta_{JA}).$
- 8: Hysteresis voltage is referenced by V_R.
- 9: Time required for V_{OUT} to reach 95% of V_R (output voltage setting), after V_{SHDN} is switched from 0 to V_{IN} .

ELECTRICAL SPECIFICATIONS (CONTINUED)

Electrical Specifications: Unless otherwise noted, $V_{IN} = V_R + 1V$, $I_L = 100 \ \mu\text{A}$, $C_L = 3.3 \ \mu\text{F}$, $\overline{\text{SHDN}} > V_{IH}$, $T_A = +25^{\circ}\text{C}$. **BOLDFACE** type specifications apply for junction temperature of -40°C to +125°C.

| Parameter | Sym | Min | Тур | Max | Units | Conditions |
|---|--------------------|-----|-----------------------|-----|------------------|---|
| Output Noise | eN | _ | 600 | _ | nV / √Hz | I _L = I _{OUTMAX} , F = 10 kHz |
| Response Time (from Shutdown Mode) | t _R | _ | 60 | _ | μs | $V_{IN} = 4V$ $C_{IN} = 1 \ \mu\text{F}, \ C_{OUT} = 10 \ \mu\text{F}$ $I_L = 0.1 \ \text{mA}, \ \text{Note 9}$ |
| SHDN Input | | | | | | |
| SHDN Input High Threshold | V _{IH} | 60 | _ | _ | %V _{IN} | V _{IN} = 2.5V to 6.0V |
| SHDN Input Low Threshold | V _{IL} | _ | _ | 15 | %V _{IN} | V _{IN} = 2.5V to 6.0V |
| ERROR OUTPUT | | | | | | |
| Minimum V _{IN} Operating Voltage | V _{INMIN} | 1.0 | _ | _ | V | I _{OL} = 0.1 mA |
| Output Logic Low Voltage | V _{OL} | _ | _ | 400 | mV | 1 mA Flows to ERROR, I _{OL} = 1 mA, V _{IN} = 2V |
| ERROR Threshold Voltage | V_{TH} | _ | 0.95 x V _R | - | V | See Figure 4-2 |
| ERROR Positive Hysteresis | V_{HYS} | _ | 50 | - | mV | Note 8 |
| V _{OUT} to ERROR Delay | t _{DELAY} | _ | 2 | | ms | V_{OUT} from V_R = 3V to 2.8V |
| Resistance from ERROR to GND | R _{ERROR} | _ | 126 | _ | Ω | V _{DD} = 2.5V, V _{OUT} = 2.5V |
| | | | | | | |

- The minimum V_{IN} has to meet two conditions: V_{IN} = 2.7V and V_{IN} = V_R + V_{DROPOUT}.
 V_R is the regulator output voltage setting. For example: V_R = 1.8V, 2.7V, 2.8V, 2.85V, 3.0V, 3.3V.

3:
$$TCV_{OUT} = \frac{(V_{OUTMAX} - V_{OUTMIN}) \times 10^6}{V_{OUT} \times \Delta T}$$

- 4: Regulation is measured at a constant junction temperature using low duty cycle pulse testing. Load regulation is tested over a load range from 1.0mA to the maximum specified output current. Changes in output voltage due to heating effects are covered by the thermal regulation specification.
- 5: Dropout voltage is defined as the input to output differential at which the output voltage drops 2% below its nominal value at a 1V differential.
- 6: Thermal Regulation is defined as the change in output voltage at a time T after a change in power dissipation is applied, excluding load or line regulation effects. Specifications are for a current pulse equal to I_{MAX} at V_{IN} = 6V for T = 10 ms.
- 7: The maximum allowable power dissipation is a function of ambient temperature, the maximum allowable junction temperature and the thermal resistance from junction-to-air (i.e. T_A , T_J , θ_{JA}).
- Hysteresis voltage is referenced by V_R.
- 9: Time required for V_{OUT} to reach 95% of V_R (output voltage setting), after V_{SHDN} is switched from 0 to V_{IN}.

TEMPERATURE CHARACTERISTICS

| Electrical Specifications: Unless otherwise noted, V_{DD} = +2.7V to +6.0V and V_{SS} = GND. | | | | | | | |
|--|----------------|-----|-----|------|-------|------------|--|
| Parameters | Sym | Min | Тур | Max | Units | Conditions | |
| Temperature Ranges: | | | | | | | |
| Extended Temperature Range | T _A | -40 | _ | +125 | °C | | |
| Operating Temperature Range | T _A | -40 | _ | +125 | °C | | |
| Storage Temperature Range | T _A | -65 | _ | +150 | °C | | |
| Thermal Package Resistances: | | | | | | | |
| Thermal Resistance, 5L-SOT-23 | θ_{JA} | _ | 255 | _ | °C/W | | |

2.0 TYPICAL PERFORMANCE CURVES

Note: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

Note: Unless otherwise indicated, $V_{IN} = V_R + 1V$, $I_L = 100 \mu A$, $C_{OUT} = 3.3 \mu F$, $\overline{SHDN} > V_{IH}$, $T_A = +25 ^{\circ}C$.

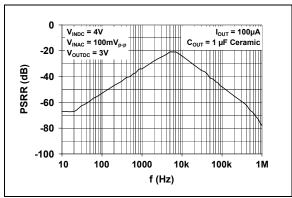


FIGURE 2-1: Power Supply Rejection Ratio.

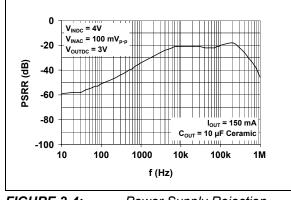


FIGURE 2-4: Power Supply Rejection Ratio.

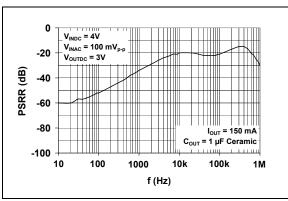


FIGURE 2-2: Power Supply Rejection Ratio.

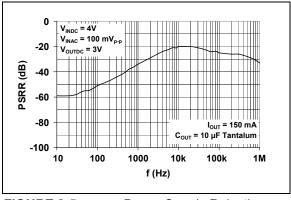


FIGURE 2-5: Power Supply Rejection Ratio.

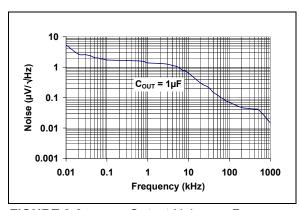


FIGURE 2-3: Output Noise vs. Frequency.

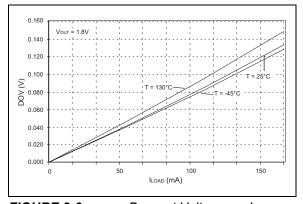


FIGURE 2-6: Dropout Voltage vs. I_{LOAD}.

Note: Unless otherwise indicated, $V_{IN} = V_R + 1V$, $I_L = 100 \mu A$, $C_{OUT} = 3.3 \mu F$, $\overline{SHDN} > V_{IH}$, $T_A = +25 ^{\circ}C$.

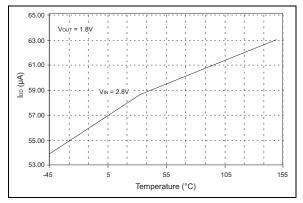


FIGURE 2-7:

 I_{DD} vs. Temperature.

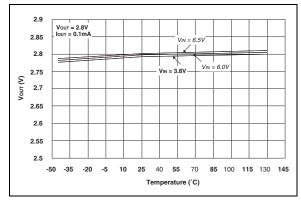


FIGURE 2-8: Temperature.

Output Voltage vs.

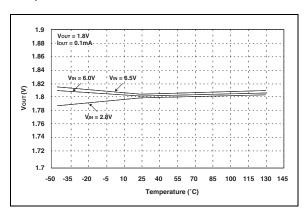


FIGURE 2-9: Temperature.

Output Voltage vs.

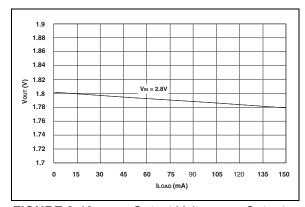


FIGURE 2-10: Current.

RE 2-10: Output Voltage vs. Output

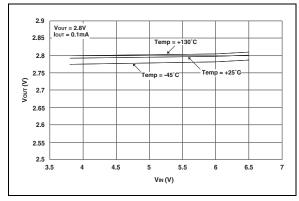


FIGURE 2-11: Voltage.

Output Voltage vs. Supply

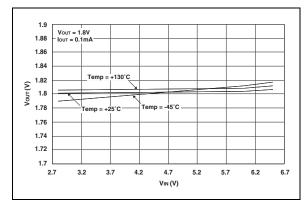


FIGURE 2-12: Voltage.

Dropout Voltage vs. Supply

Note: Unless otherwise indicated, $V_{IN} = V_R + 1V$, $I_L = 100 \mu A$, $C_{OUT} = 3.3 \mu F$, $\overline{SHDN} > V_{IH}$, $T_A = +25 ^{\circ}C$.

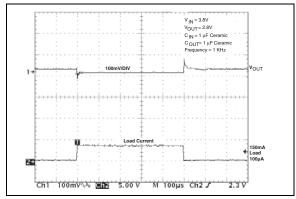
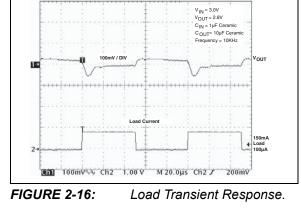


FIGURE 2-13: Load Transient Response.



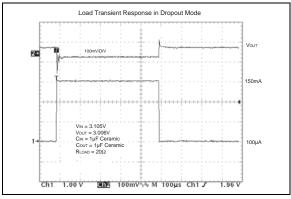


FIGURE 2-14: Load Transient Response in Dropout Mode.

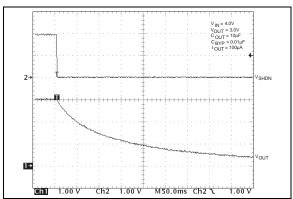


FIGURE 2-17: Shutdown Delay.

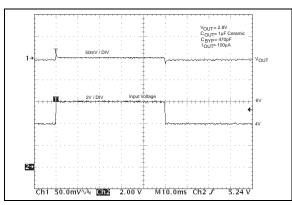


FIGURE 2-15: Line Transient Response.

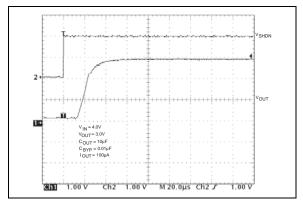


FIGURE 2-18: Shutdown Wake-up Time.

Note: Unless otherwise indicated, V_{IN} = V_R + 1V, I_L = 100 μ A, C_{OUT} = 3.3 μ F, \overline{SHDN} > V_{IH} , T_A = +25°C.

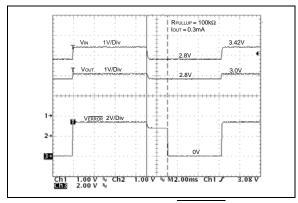


FIGURE 2-19: V_{OUT} to \overline{ERROR} Delay.

3.0 PIN DESCRIPTIONS

The descriptions of the pins are listed in Table 3-1.

TABLE 3-1: PIN FUNCTION TABLE

| Pin Number | Symbol | Description |
|------------|------------------|---|
| 1 | V _{IN} | Unregulated supply input. |
| 2 | GND | Ground terminal. |
| 3 | SHDN | Shutdown control input. The regulator is fully enabled when a logic high is applied to this input. The regulator enters shutdown when a logic low is applied to this input. During shutdown, output voltage falls to zero, ERROR is open circuited and supply current is reduced to $0.5\mu A$ (max). |
| 4 | ERROR | Out-of-Regulation Flag. (Open-drain output). This output goes low when V _{OUT} is out-of-tolerance by approximately -5%. |
| 5 | V _{OUT} | Regulated voltage output. |

3.1 Unregulated Supply Input (V_{IN})

Connect the unregulated input supply to the V_{IN} pin. If there is a large distance between the input supply and the LDO regulator, some input capacitance is necessary for proper operation. A 1 μF capacitor, connected from V_{IN} to ground, is recommended for most applications.

3.2 Ground Terminal (GND)

Connect the unregulated input supply ground return to GND. Also connect one side of the 1 μ F typical input decoupling capacitor close to this pin and one side of the output capacitor C_{OLIT} to this pin.

3.3 Shutdown Control Input (SHDN)

The regulator is fully enabled when a logic-high is applied to \overline{SHDN} . The regulator enters shutdown when a logic-low is applied to this input. During shutdown, the output voltage falls to zero and the supply current is reduced to 0.5 μ A (max).

3.4 Out-of-Regulation Flag (ERROR)

The open-drain ERROR flag provides indication that the regulator output voltage is not in regulation. The ERROR pin will be low when the output is typically below 5% of its specified value.

3.5 Regulated Voltage Output (V_{OUT})

Connect the output load to V_{OUT} of the LDO. Also connect one side of the LDO output decoupling capacitor as close as possible to the V_{OUT} pin.

4.0 DETAILED DESCRIPTION

The TC2054, TC2055 and TC2186 are precision fixed output voltage regulators. (If an adjustable version is desired, refer to the TC1070/TC1071/TC1187 data sheet (DS21353). Unlike bipolar regulators, the TC2054, TC2055 and TC2186 supply current does not increase with load current. In addition, V_{OUT} remains stable and within regulation over the entire 0 mA to maximum output current operating load range.

Figure 4-1 shows a typical application circuit. The regulator is enabled any time the shutdown input (SHDN) is at or above V_{IH} , and shutdown (disabled) when SHDN is at or below V_{IL} . SHDN may be controlled by a CMOS logic gate, or I/O port of a microcontroller. If the SHDN input is not required, it should be connected directly to the input supply. While in shutdown, supply current decreases to 0.05 μ A (typical), V_{OUT} falls to zero volts, and ERROR is open-circuited.

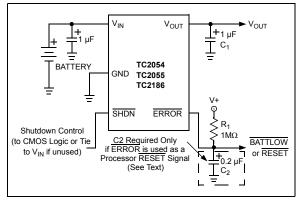


FIGURE 4-1: Typical Application Circuit.

4.1 ERROR Open-Drain Output

ERROR is driven low whenever V_{OUT} falls out of regulation by more than -5% (typical). This condition may be caused by low input voltage, output current limiting or thermal limiting. The ERROR threshold is 5% below rated V_{OUT} regardless of the programmed output voltage value (e.g. ERROR = V_{OL} at 4.75V (typ.) for a 5.0V regulator and 2.85V (typ.) for a 3.0V regulator). ERROR output operation is shown in Figure 4-2.

Note that $\overline{\text{ERROR}}$ is active when V_{OUT} falls to V_{TH} , and inactive when V_{OUT} rises above V_{TH} by V_{HYS} .

As shown in Figure 4-1, $\overline{\text{ERROR}}$ can be used as a battery low flag or as a processor $\overline{\text{RESET}}$ signal (with the addition of timing capacitor C_2). $R_1 \times C_2$ should be chosen to maintain $\overline{\text{ERROR}}$ below V_{IH} of the processor $\overline{\text{RESET}}$ input for at least 200 ms to allow time for the system to stabilize. Pull-up resistor R_1 can be tied to V_{OUT} , V_{IN} or any other voltage less than $(V_{IN} + 0.3V)$. The $\overline{\text{ERROR}}$ pin sink current is self-limiting to approximately 18 mA.

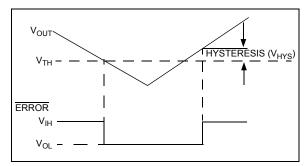


FIGURE 4-2:

Error Output Operation.

4.2 Output Capacitor

A 1 µF (min) capacitor from V_{OUT} to ground is required. The output capacitor should have an effective series resistance of 0.01 $\!\Omega$. to 5Ω for V_{OUT} = 2.5V, and 0.05 $\!\Omega$. to 5Ω for V_{OUT} < 2.5V. Ceramic, tantalum and aluminum electrolytic capacitors can be used. (Since many aluminum electrolytic capacitors freeze at approximately -30°C, solid tantalums recommended for applications operating below -25°C). When operating from sources other than batteries. supply-noise rejection and transient response can be improved by increasing the value of the input and output capacitors and employing passive filtering techniques.

4.3 Input Capacitor

A 1 μ F capacitor should be connected from V_{IN} to GND if there is more than 10 inches of wire between the regulator and this AC filter capacitor, or if a battery is used as the power source. Aluminum electrolytic or tantalum capacitors can be used (since many aluminum electrolytic capacitors freeze at approximately -30°C, solid tantalum are recommended for applications operating below -25°C). When operating from sources other than batteries, supply-noise rejection and transient response can be improved by increasing the value of the input and output capacitors and employing passive filtering techniques.

5.0 THERMAL CONSIDERATIONS

5.1 Thermal Shutdown

Integrated thermal protection circuitry shuts the regulator off when the die temperature exceeds approximately 160°C. The regulator remains off until the die temperature cools to approximately 150°C.

5.2 Power Dissipation

The amount of power the regulator dissipates is primarily a function of input and output voltage, and output current.

Equation 5-1 is used to calculate worst case power dissipation:

EQUATION 5-1:

 $P_D \approx (V_{INMAX} - V_{OUTMIN})I_{LOADMAX}$

Where:

P_D = Worst-case actual power dissipation

 V_{INMAX} = Maximum voltage on V_{IN}

V_{OUTMIN} = Minimum regulator output voltage

 $I_{LOADMAX}$ = Maximum output (load) current

The maximum allowable power dissipation (Equation 5-2) is a function of the maximum ambient temperature (T_{AMAX}), the maximum allowable die temperature (125 °C) and the thermal resistance from junction-to-air (θ_{JA}). The 5-Pin SOT-23A package has a θ_{JA} of approximately 220°C/Watt when mounted on a typical two layer FR4 dielectric copper clad PC board.

EQUATION 5-2:

$$P_{DMAX} = \frac{T_{JMAX} - T_{AMAX}}{\theta_{JA}}$$

Where all terms are previously defined.

Equation 5-1 can be used in conjunction with Equation 5-2 to ensure regulator thermal operation is within limits. For example:

Given:

 V_{INMAX} = 3.0V +10% V_{OUTMIN} = 2.7V - 2.5% $I_{LOADMAX}$ = 40 mA T_{AMAX} = +55°C

Find:

- 1. Actual power dissipation
- 2. Maximum allowable dissipation

Actual power dissipation:

$$\begin{split} P_D &= (V_{INMAX} - V_{OUTMIN}) I_{LOADMAX} \\ &= [(3.0 \times 1.1) - (2.7 \times 0.975)] 40 \times 10^{-3} \\ &= 26.7 mW \end{split}$$

Maximum allowable power dissipation:

$$P_{DMAX} = \frac{T_{JMAX} - T_{AMAX}}{\theta_{JA}}$$
$$= \frac{125 - 55}{220}$$
$$= 318mW$$

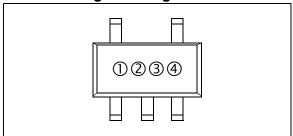
In this example, the TC2054 dissipates a maximum of only 26.7 mW; far below the allowable limit of 318 mW. In a similar manner, Equation 5-1 and Equation 5-2 can be used to calculate maximum current and/or input voltage limits.

5.3 Layout Considerations

The primary path of heat conduction out of the package is via the package leads. Therefore, layouts having a ground plane, wide traces at the pads, and wide power supply bus lines combine to lower θ_{JA} and, therefore, increase the maximum allowable power dissipation limit.

6.0 PACKAGING INFORMATION

6.1 Package Marking Information



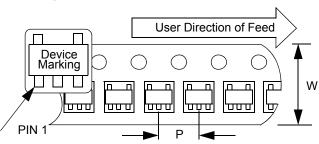
- ① & ② represents part number code + temperature range and voltage
- 3 represents year and 2-month period code
- Prepresents lot ID number

TABLE 6-1: PART NUMBER CODE AND TEMPERATURE RANGE

| (V) | TC2054 | TC2055 | TC2186 |
|------|--------|--------|--------|
| 1.8 | SA | TA | VA |
| 2.5 | SB | TB | VB |
| 2.7 | SC | TC | VC |
| 2.8 | SD | TD | VD |
| 2.85 | SE | TE | VE |
| 3.0 | SF | TF | VF |
| 5.0 | SJ | TG | VG |

6.2 Taping Information

Component Taping Orientation for 5-Pin SOT-23A (EIAJ SC-74A) Devices

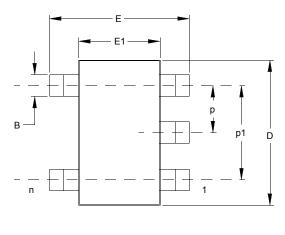


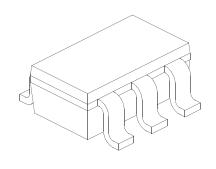
Standard Reel Component Orientation for 713 Suffix Device (Mark Right Side Up)

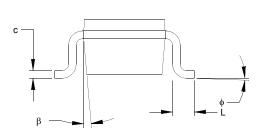
Carrier Tape, Number of Components Per Reel and Reel Size:

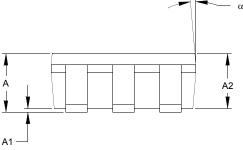
| Package | Carrier Width (W) | Pitch (P) | Part Per Full Reel | Reel Size |
|---------------|-------------------|-----------|--------------------|-----------|
| 5-Pin SOT-23A | 8 mm | 4 mm | 3000 | 7 in. |

5-Lead Plastic Small Outline Transistor (CT) (SOT-23)









| | Units | INCHES* | | | MILLIMETERS | | |
|----------------------------|-------|---------|---------|------|-------------|------|------|
| Dimension Lim | its | MIN | MIN NOM | | MIN | NOM | MAX |
| Number of Pins | n | | 5 | | | 5 | |
| Pitch | р | | .038 | | | 0.95 | |
| Outside lead pitch (basic) | p1 | | .075 | | | 1.90 | |
| Overall Height | Α | .035 | .046 | .057 | 0.90 | 1.18 | 1.45 |
| Molded Package Thickness | A2 | .035 | .043 | .051 | 0.90 | 1.10 | 1.30 |
| Standoff | A1 | .000 | .003 | .006 | 0.00 | 0.08 | 0.15 |
| Overall Width | Е | .102 | .110 | .118 | 2.60 | 2.80 | 3.00 |
| Molded Package Width | E1 | .059 | .064 | .069 | 1.50 | 1.63 | 1.75 |
| Overall Length | D | .110 | .116 | .122 | 2.80 | 2.95 | 3.10 |
| Foot Length | L | .014 | .018 | .022 | 0.35 | 0.45 | 0.55 |
| Foot Angle | f | 0 | 5 | 10 | 0 | 5 | 10 |
| Lead Thickness | С | .004 | .006 | .008 | 0.09 | 0.15 | 0.20 |
| Lead Width | В | .014 | .017 | .020 | 0.35 | 0.43 | 0.50 |
| Mold Draft Angle Top | а | 0 | 5 | 10 | 0 | 5 | 10 |
| Mold Draft Angle Bottom | b | 0 | 5 | 10 | 0 | 5 | 10 |

^{*} Controlling Parameter

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .005" (0.127mm) per side. EIAJ Equivalent: SC-74A

Drawing No. C04-091

Revised 09-12-05

APPENDIX A: REVISION HISTORY

Revision C (May 2006)

- Page 1: Added overtemperature to bullet for overcurrent protection in features and general description verbiage.
- Page 3: Added "Thermal Shutdown Die Temperature" to electrical characteristics table. Changed codition for "Minimum V_{IN} Operating Voltage"
- Page 3: Added Thermal Characteristics Table.
- Page 5: Added new section 5.1 and new verbiage.
- · Page 13: Updated package outline drawing.

Revision B (May 2002)

· Data Sheet converted to Microchip standards.

Revision A (May 2001)

· Original Release of this Document under Telcom.

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

| PART NOX | <u>x xxxx</u> | Ex | amples: |
|--------------------|--|----|--|
| | put Temperature Package | a) | TC2054-1.8VCTTR: 5LD SOT-23-A, 1.8V, Tape and Reel. |
| Volt | age Range | b) | TC2054-2.85VCTTR: 5LD SOT-23-A, 2.85V, Tape and Reel. |
| Device: | TC2054: 50 mA LDO with Shutdown and ERROR Output TC2055: 100 mA LDO with Shutdown and ERROR Output TC2186: 150 mA LDO with Shutdown and ERROR Output | c) | TC2054-3.3VCTTR: 5LD SOT-23-A, 3.3V, Tape and Reel. |
| Output Voltage: | XX = 1.8V | a) | TC2055-1.8VCTTR: 5LD SOT-23-A, 1.8V, Tape and Reel. |
| Output Voltage. | XX = 2.5V XX = 2.7V | b) | TC2055-2.85VCTTR: 5LD SOT-23-A, 2.85V, Tape and Reel. |
| | XX = 2.8V XX = 2.85V XX = 3.0V | c) | TC2055-3.0VCTTR: 5LD SOT-23-A, 3.0V, Tape and Reel. |
| | XX = 3.3V | a) | TC2186-1.8VCTTR: 5LD SOT-23-A, 1.8V, Tape and Reel. |
| Temperature Range: | V = -40°C to +125°C | b) | TC2186-2.8VCTTR: 5LD SOT-23-A, 2.8V, Tape and Reel. |
| Package: | CTTR = Plastic Small Outline Transistor (SOT-23), 5-lead, Tape and Reel | | |

NOTES:

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